# **SPECIFICATION**

May-08-2012

### **OF**

## LIQUID CRYSTAL DISPLAY MODULE

Model No. :	UMSH-8252MD-T(REV1)	
Model version		
Document Revis	sion:4	

CUSTOMER APPROVED SIGNATURE						

This specification need to be signed by purchaser or customer as a specification of products production and delivery from URT. Without signature of this specification, any purchase order for this model no. will be treated and considered that this specification is automatically acknowledged and accepted by purchaser or customer.



Allen WangGeorge TsengAngus ChiuSharon TsaiMay-08-2012APPROVEDCHECKEDCHECKEDPREPAREDDate

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To Whom It May Concern:

In continuing to develop and promote the strategic partnership between United Radiant Technology (URT) and Microtips USA (MTUSA), URT is please to announce that we have entered into an agreement with MTUSA to support some key projects only through MTUSA and as such the attached spec with URT Part no. will be manufactured by URT but support and logistic of the sales will be handled by MTUSA.

URT is confident that this arrangement between our two companies will ultimately benefit the end customer.

Thank You. Raymond Chen

Sales Manager: URT

		Revision record	
Document	Model No.	Description	Revision
Revision	Version No.	Description	by
0	UMSH-8252MD-T Version No. 0		H.C. Lin Jeffry Chen 19-Nov-2008
1	UMSH-8252MD-T Version No. 1	Modify the initial code.	Yu-Lun TSENG Jeffry Chen 31-Jul-2009
2	UMSH-8252MD-T Version No. 2	Modify the Back-light only Specification.	Jeffry Chen Ken Lin 17-Sep-2009
3	UMSH-8252MD-T Version No. 3	Modify the initial code.	Jeffry Chen Ken Lin 05-Mar-2010
4	UMSH-8252MD-T(REV1) (UFSH-K140EY-FT) Version No. 0	<ol> <li>Change the TFT glass.</li> <li>Revise the Command for new TFT glass.</li> <li>Modify the module number from UMSH-8252MD-T to UMSH-8252MD-T(REV1).</li> </ol>	William Don Jeffry Chen 25-Apr-2012
//////////////////////////////////////	crotips hnology Revision 4; I	UMSH-8252MD-T(REV1) Ver. 0 ; May-08-2012	Page: 2

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#### 1. BASIC SPECIFICATION

1.1 Mechanical specifications

dechanical specifications		
Items	Nominal Dimension	Unit
Active screen size	3.5" diagonal	-
Dot Matrix	320*RGB*240	dots
Module Size (W x H x T)	76.9 x 63.9 x 3.2	mm.
Active Area (W x H)	70.08 x 52.56	mm.
Dot Pitch (W x H)	0.219 x 0.219	mm.
Color depth	262K	color
Interface	1. 8/9/ 16/ 18-bit 6800-series / 8080-series Parallel Interface 2. Serial Peripheral Interface (SPI) 3. 18-/6-bit RGB interface (DEN, DOTCLK, HSYNC, VSYNC, DB[17:0]) + 3-wire SPI 4. VSYNC interface (system interface + VSYNC) 5. WSYNC interface (system interface + WSYNC)	-
Driving IC Package	COG	-
Module weight	32±10%	g

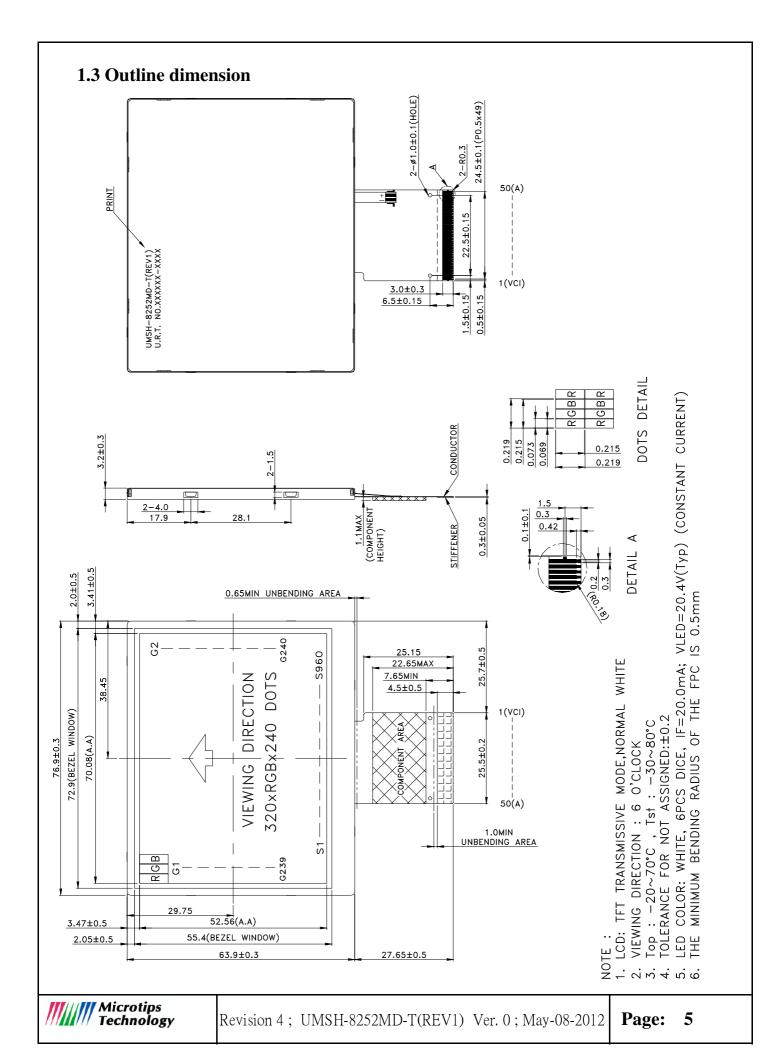
<sup>\*</sup> The maximum color depth of this driver IC is 262K colors, not 16.7M.

1.2 Display specification

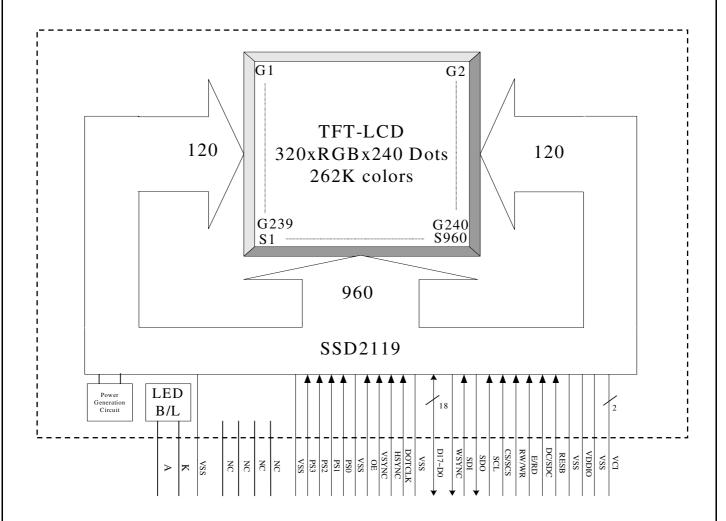
Display	Descriptions	Note
LCD Type	CD Type a-Si TFT	
LCD Mode	TN / Normal white	-
Polarizer Mode	Transmissive	-
Polarizer Surface	Normal	-
Pixel arrangement	RGB-stripe	-
Backlight Type	LED	-
Viewing Direction(Gray inversion)	6 O'clock Direction	1

Color tone is slightly changed by temperature and driving voltage.

Note 1: The viewing direction defined in this specification follows the rubbing direction of its mother TFT surface treatment. The grayscale inversion is at this direction as well. The optimized viewing direction applied into end-device is decided by customers.



# 1.4 Block diagram:



# 1.5 Interface pin:

Pin No.	Pin Name	I/O	Description
1~2	VCI	P	Booster input voltage pin.
3	VSS	P	System ground pin of the IC.
4	VDDIO	P	Voltage input pin for logic I/O.
5	VSS	P	System ground pin of the IC.
6	RESB	I	System reset pin.  - An active low pulse at this pin will reset the IC, Connect to VDDIO in normal operation.
7	DC/SDC	I	Data or command.  DC : Parallel Interface.  SDC : Serial Interface.
8	E/RD	I	6800-system : E (enable signal) 8080-system : RD (read strobe signal) Serial mode : Not used and should be connected to VDDIO or Vss.
9	RW/WR	I	6800-system: RW (indicates read cycle when High, write cycle when Low) 8080-system: WR (write strobe signal)
10	CS/SCS	I	CS: Chip Select pin for 6800/8080 Parallel Interface. SCS: Chip Select pin for Serial Mode Interface.
11	SCL	I	Serial clock input.
12	SDO	0	Data output pin in serial interface.
13	SDI	I	Data input pin in serial interface.
14	WSYNC	О	Ram Write Synchronization outputLeave it OPEN when not used.

Pin No.	Pin Name	I/O	Description			
15	D17					
16	D16	]				
17	D15	1				
18	D14	]				
19	D13	]				
20	D12	]				
21	D11	]				
22	D10	]				
23	D9	1	For parallel mode, 8/9/16/18 bit interface.			
24	D8	I/O	Please refer to Table 1.			
25	<b>D</b> 7	]	Unused pins should connect to VSS.			
26	D6	1				
27	D5	1				
28	D4	1				
29	D3	1				
30	D2	]				
31	D1	1				
32	D0	]				
33	VSS	P	System ground pin of the IC.			
34	DOTCLK	I	Dot-clock signal and oscillator source.			
35	HSYNC	I	Line Synchronization input.			
36	VSYNC	I	Frame/Ram Write Synchronization input.			
37	OE	I	Display enable pin from controller.			
38	VSS	P	System ground pin of the IC.			
39	PS0					
40	PS1	I	Please refer to Table 1.			
41	PS2		Ticase refer to Table 1.			
42	PS3					
43	VSS	P	System ground pin of the IC.			
44	NC	-	No connection.			
45	NC	-	No connection.			



Pin No.	Pin Name	I/O	Description		
46	NC	-	No connection.		
47	NC	-	No connection.		
48	VSS	P	System ground pin of the IC.		
49	K	P	Backlight LED's cathode.		
50	A	P	Backlight LED's anode.		

## Table 1.

PS3	PS2	PS1	PS0	Interface Mode	Data bus input
0	0	0	0	16-bit 6800 parallel interface	D[17:10], D[8:1]
0	0	0	1	8-bit 6800 parallel interface	D[17:10]
0	0	1	0	16-bit 8080 parallel interface	D[17:10], D[8:1]
0	0	1	1	8-bit 8080 parallel interface	D[17:10]
0	1	0	0	9-bit generic D[9:16] (262k colour) + 3-wire SPI If 65K color, D12 shorts to D17 internally	
0	1	0	1	16-bit generic (262k colour) + 3-wire SPI	
0	1	1	0	18-bit generic (262k colour) + 3-wire SPI	
0	1	1	1	6-bit generic D[8:3] (262k colour) + 3-wire SPI	
1	0	0	0	18-bits 6800 parallel interface	D[17:0]
1	0	0	1	9-bits 6800 parallel interface	D[17:9]
1	0	1	0	18-bit 8080 parallel interface	D[17:0]
1	0	1	1	9-bit 8080 parallel interface	D[17:9]
1	1	1	0	3-wire SPI	
1	1	1	1	4-wire SPI	

# 2. ELECTRICAL CHARACTERISTICS

## 2.1 Absolute Maximum Ratings

Items	Symbol	Min.	Max.	Unit	
Input voltage	VCI	VSS-0.3	5.0	V	
Supply Voltage	VDDIO	VSS-0.3	4.0	V	
Operate temperature range	ТОР	-20	70	°C	
Storage temperature range	TST	-30	80	°C	

### 2.2 DC Characteristics

Items	Symbol	Min.	Тур.	Max.	Unit	Condition
Power supply voltage	VCI	2.5	3.3	3.6	V	
Power supply pin of IO pins	VDDIO	1.4	3.3	3.6	v	
Current consumption	IVCI+IVDDIO	-	-	10	mA	NOTE
Dot Clock	DCK	-	5.5	8.2	MHz	

NOTE: The method to illuminate the LCD panel is using the 2-5-4commend under the measuring condition.

Measuring Condition:

Standard Value MAX.

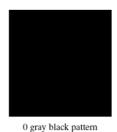
= 25°C Ta

 $\mathbf{V}_{\mathrm{CI}}$ = 3.3V

VDDIO = 3.3V

Dot Clock = 5.5 MHz

Display Patten = Checkered pattern



## 2-2.1 Back-light Characteristics

Parameter	Symbol	Min	Тур	Max	Unit	Test Condition	Note
Supply Current	If	1	20	1	mA	Ta=25°℃	1
Supply Voltage	VF	18.6	20.4	22.2	V	Ta=25°℃	-
Half-Life Time	Lf	-	50000	1	hrs	Ta=25°℃	1

Note1: The "Half-Life Time" is defined as the LED chip brightness decreases to 50% than original brightness, Based on Ta 25±2°C ,60±10% RH condition.

# 2.3 Command ( Recommend by U.R.T.)

1. LCD\_Initial\_SSD2119:(for 16bit 8080 interface)

COMMAND	CODE	DESCRIPTION
R00H	0001	OSCEN=1
R10H	0000	Sleep=0
R07H	0033	Display control. CM=0
DIIII	6970	65K color, X, Y auto increase ,updated in
R11H	6870	horizontal direction
R02H	0600	line inversion
R03H	4A38	VGH/VGL= 5/-3
R01H	72EF	Gate lines =240
R0FH	0000	Start scan line = 0
R25H	A000	Frame frequency
R28H	0006	Enable R25, R29 register
R12H	0999	Sleep mode
R26H	3800	Analogue setting
R0BH	5308	Frequency
R0CH	0004	VCIX2
R0DH	000A	VLCD63
R0EH	2600	VCOML
R1EH	00 AF	VCOMH
R44H	EF00	HAS and HEA station
R45H	0000	Vertical address start station
R46H	013F	Vertical address end station
R30H	0000	Gamma B control 1
R31H	0101	Gamma B control 2
R32H	0100	Gamma B control 3
R33H	0305	Gamma B control 4
R34H	0707	Gamma B control 5
R35H	0305	Gamma B control 6
R36H	0707	Gamma B control 7
R37H	0201	Gamma B control 8
R3 AH	1200	Gamma B control 9
R3BH	0900	Gamma B control 10
R22H		Write data to RAM

## 2. LCD\_Initial\_SSD2119:(for 18bit+3wire SPI and 4wire SPI)

COMMAND	CODE	DESCRIPTION
R00H	0001	OSCEN=1
R10H	0000	Sleep=0
R07H	0033	Display control. CM=0
		DFM[1:0]: 262k Color Mode
		DenMode = 1 : RGB interface ignore
R11H	4E70	HSYNC, VSYNC pin and HBP, VBP
		WMode = 1 : Write RAM from Generic
		RGB data (POR, if PS:00xx)
R02H	0600	line inversion
R03H	6A38	VGH/VGL= 5/-3
R01H	72EF	Gate lines =240
R28H	0006	Enable R25, R29 register
R12H	0999	Sleep mode
R26H	3800	Analogue setting
R0CH	0004	VCIX2
R0DH	000A	VLCD63
R0EH	2600	VCOML
R1EH	00AF	VCOMH
R15H	0058	Entry mode
R30H	0000	Gamma B control 1
R31H	0101	Gamma B control 2
R32H	0100	Gamma B control 3
R33H	0305	Gamma B control 4
R34H	0707	Gamma B control 5
R35H	0305	Gamma B control 6
R36H	0707	Gamma B control 7
R37H	0201	Gamma B control 8
R3 AH	1200	Gamma B control 9
R3BH	0900	Gamma B control 10
R22H		Write data to RAM

## 2.5 AC Characteristics

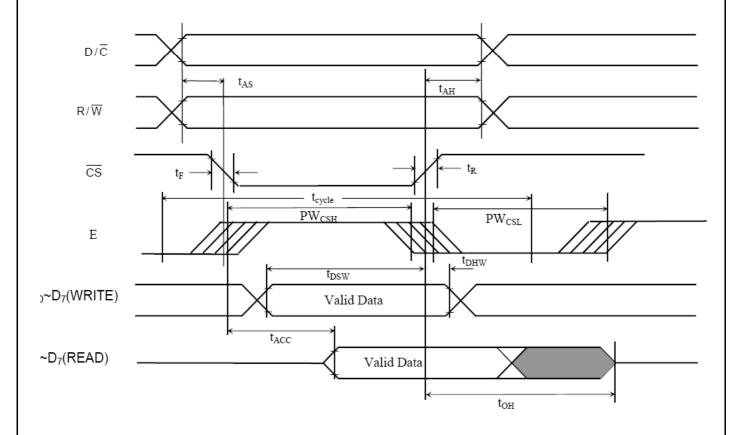
## 2-4-1 Parallel 6800 Timing Characteristics

 $(T_A = -40 \text{ to } 85^{\circ}\text{C}, V_{DDIO} = 1.4 \text{V to } 3.6 \text{V})$ 

Symbol	Parameter	Min	Тур	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time (write cycle)	75	-	-	ns
t <sub>cycle</sub>	Clock Cycle Time (read cycle)	1000	-	-	ns
t <sub>AS</sub>	Address Setup Time (R/W)	0	-	-	ns
t <sub>AH</sub>	Address Hold Time $(R/\overline{W})$	0	-	-	ns
t <sub>DSW</sub>	Data Setup Time (D0~D7, WRITE)	5	-	-	ns
t <sub>DHW</sub>	Data Hold Time (D0~D7, WRITE))	5	-	-	ns
t <sub>ACC</sub>	Data Access Time (D0~D7, READ)	250	-	-	ns
toH	Output Hold time (D0~D7, READ)	100	-	-	ns
PW <sub>CSL</sub>	Pulse width /CS low (write cycle)	40	-	-	ns
PWcsh	Pulse width /CS high (write cycle)	25	-	-	ns
PW <sub>CSL</sub>	Pulse width /CS low (read cycle)	500	-	-	ns
PWcsh	Pulse width /CS high (read cycle)	500	-	-	ns
t <sub>R</sub>	Rise time (/CS)	-	-	4	ns
$t_{F}$	Fall time (/CS)	_	-	4	ns

Note: CS can be pulled low during the write cycle, only /RW is needed to be toggled

### Parallel 6800-series Interface Timing Characteristics



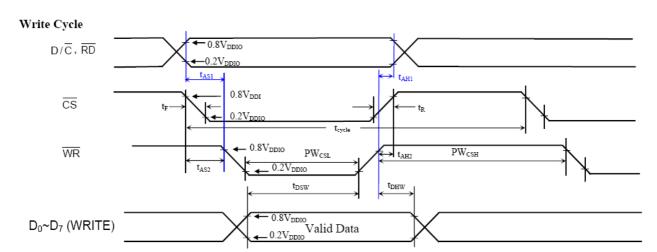
## 2-4-2 Parallel 8080 Timing Characteristics

 $(T_A = -40 \text{ to } 85^{\circ}\text{C}, V_{DDIO} = 1.4 \text{V to } 3.6 \text{V})$ 

Symbol	Parameter	Min	Тур	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time (write cycle)	75	-	-	ns
t <sub>cycle</sub>	Clock Cycle Time (read cycle)	1000	-	-	ns
t <sub>AS1</sub>	Address Setup Time between (R/ $\overline{\mathrm{W}}$ ) and D/ $\overline{\mathrm{C}}$	0	-	-	ns
t <sub>AH1</sub>	Address Hold Time between ( $R/\overline{W}$ ) and $D/\overline{C}$	0	-	-	ns
t <sub>AS2</sub>	Address Setup Time between ( $R/\overline{W}$ ) and $\overline{CS}$	0	-	-	ns
t <sub>AH2</sub>	Address Hold Time between ( $R/\overline{W}$ ) and $\overline{CS}$	0	-	-	ns
t <sub>DSW</sub>	Data Setup Time (D0~D7, WRITE)	5	-	-	ns
t <sub>DHW</sub>	Data Hold Time (D0~D7, WRITE))	5	-	-	ns
t <sub>ACC</sub>	Data Access Time (D0~D7, READ)	250	-	-	ns
t <sub>OH</sub>	Output Hold time (D0~D7, READ)	100	-	-	ns
PW <sub>CSL</sub>	Pulse width /CS low (write cycle)	40	-	-	ns
PWcsh	Pulse width /CS high (write cycle)	25	-	-	ns
PW <sub>CSL</sub>	Pulse width /CS low (read cycle)	500	-	-	ns
PWcsh	Pulse width /CS high (read cycle)	500	-	-	ns
t <sub>R</sub>	Rise time (/CS)	-	-	4	ns
$t_{F}$	Fall time (/CS)	-	-	4	ns

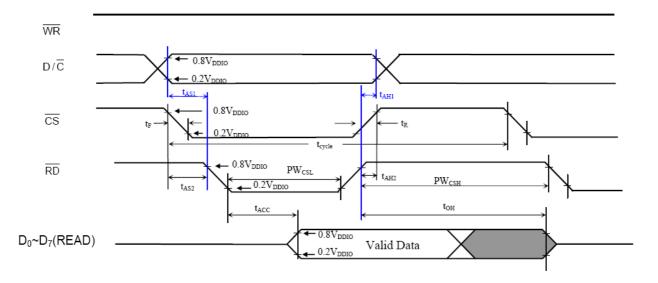
Note: CS can be pulled low during the write cycle, only /RW is needed to be toggled

### Parallel 8080-series Interface Timing Characteristics



Remark: It's highly recommended that  $\overline{\text{RD}}$  remains high for the whole write cycle

#### Read Cycle



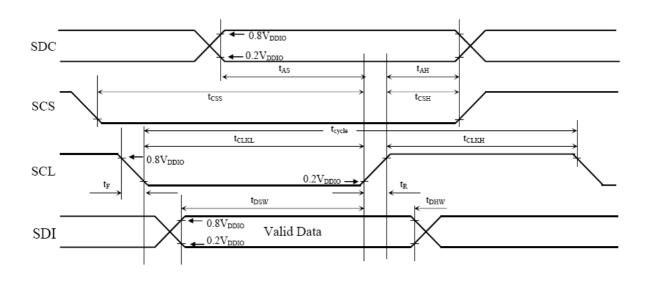
///////// Microtips Technology

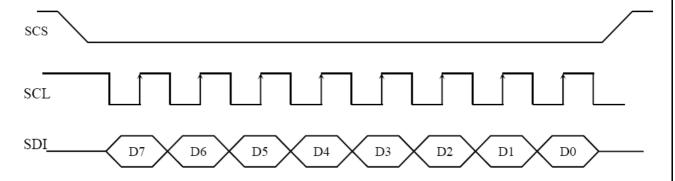
# 2-4-3 Serial Timing Characteristics

(T<sub>A</sub> = -40 to 85°C,  $V_{DDIO}$  = 1.4V to 3.6V )

Symbol	Parameter	Min	Тур	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	77	-	-	ns
f <sub>CLK</sub>	Serial Clock Cycle Time SPI Clock tolerance = +/- 2 ppm	-	-	15	MHz
t <sub>AS</sub>	Register select Setup Time	4	-	-	ns
t <sub>AH</sub>	Register select Hold Time	5	-	-	ns
t <sub>CSS</sub>	Chip Select Setup Time	2	-	-	ns
t <sub>CSH</sub>	Chip Select Hold Time	10	-	-	ns
t <sub>DSW</sub>	Write Data Setup Time	5	-	-	ns
t <sub>OHW</sub>	Write Data Hold Time	10	-	-	ns
t <sub>CLKL</sub>	Clock Low Time	38	-	-	ns
t <sub>CLKH</sub>	Clock High Time	38	-	-	ns
t <sub>R</sub>	Rise time	-	-	4	ns
t <sub>F</sub>	Fall time	-	-	4	ns

### 4 wire Serial Timing Characteristics





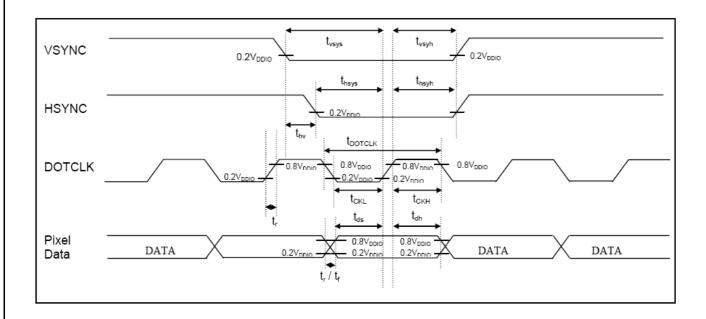
# 2-4-4 RGB Timing Characteristics

 $(T_A = -40 \text{ to } 85^{\circ}\text{C}, V_{DDIO} = 1.4 \text{V to } 3.6 \text{V})$ 

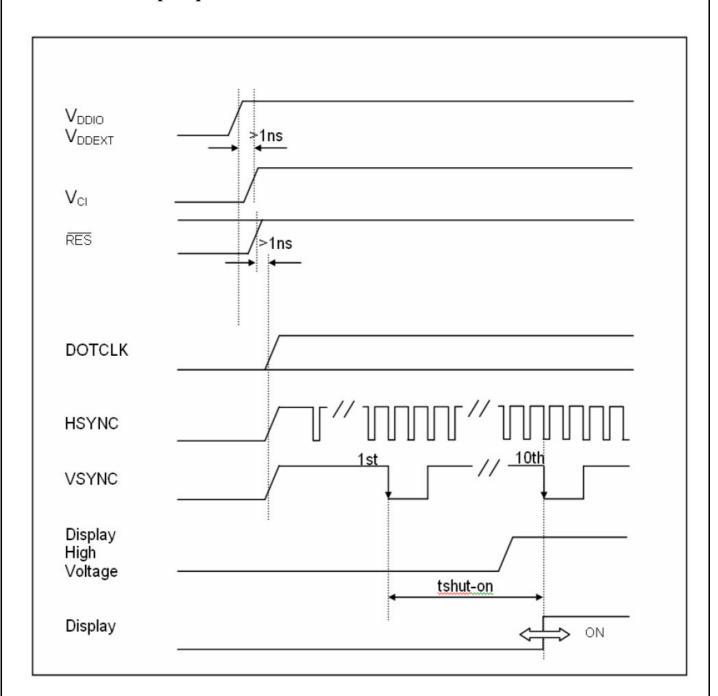
Symbol	Parameter	Min	Тур	Max	Unit
fDOTCLK	DOTCLK Frequency (70Hz frame rate)	1	5.5	8.2	MHz
tDOTCLK	DOTCLK Period	122	182	1000	us
t <sub>VSYS</sub>	Vertical Sync Setup Time	20	-	-	ns
t <sub>VSYH</sub>	Vertical Sync Hold Time	20	-	-	ns
t <sub>HSYS</sub>	Horizontal Sync Setup Time	20	-	-	ns
t <sub>HSYH</sub>	Horizontal Sync Hold Time	20	-	-	ns
t <sub>HV</sub>	Phase difference of Sync Signal Falling Edge	0	-	320	tDOTCLK
t <sub>CLK</sub>	DOTCLK Low Period	61	-	-	ns
t <sub>CKH</sub>	DOTCLK High Period	61	-	-	ns
t <sub>DS</sub>	Data Setup Time	25	-	-	ns
t <sub>DH</sub>	Data hold Time	25	-	-	ns
t <sub>RES</sub>	Reset pulse width	8			ns

Note: External clock source must be provided to DOTCLK pin of SSD2119. The driver will not operate in absence of the clocking signal.

## **RGB Timing Characteristics**



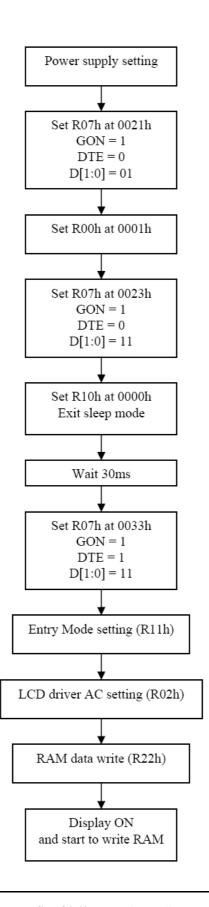
# 2-4-5 Power Up Sequence



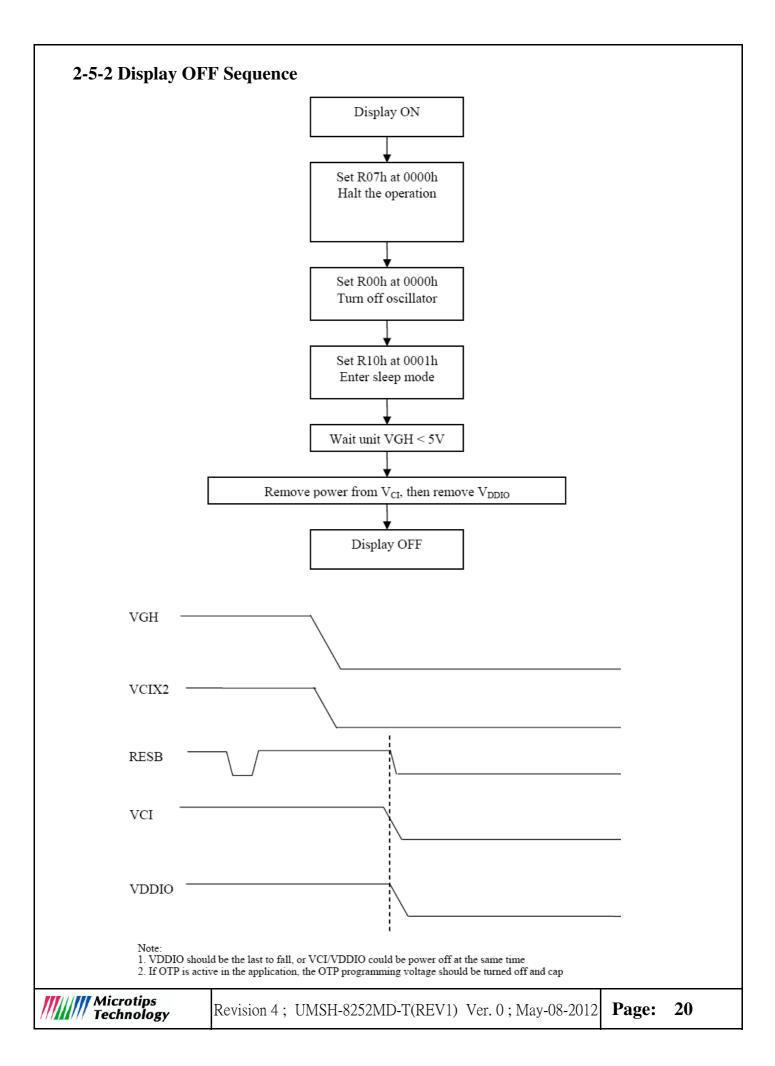
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## 2-5 DISPLAY SETTING SEQUENCE

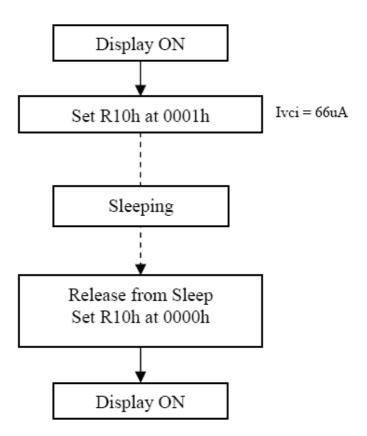
## 2-5-1 Display ON Sequence







# 2-5-3 Sleep Mode Display Sequence



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## 3. OPTICAL CHARACTERISTICS

## 3.1 Characteristics

Electrical and Optical Characteristics

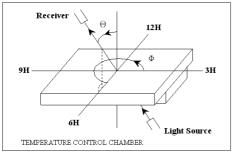
No.	Item			symbo	l / temp.	Min.	Тур.	Max.	Unit	Note
1	Response	Time	e	Tr+Tf	$\Theta = \Psi = 0^{\circ}$	ı	25	-	ms	2
		Hor.	or. Cr>=10 $\begin{array}{c ccccccccccccccccccccccccccccccccccc$							
	Viewing		Cm 10	$\Theta_2$	180°	60	70	-	daamaa	2
2	Angle	Man	Cr>=10		270°	60	70	-	degree	3
		Ver.			90°	45	60	-		
3	Contrast	Ratio		Cr	25 ℃	400	700		-	4
	Red x-co	de		Rx		0.55	0.60	0.65	degree 3 - 4	
	Red y-co	de		Ry		0.28	0.33	0.38		
	Green x-c	code		Gx		0.31	0.36	0.41		
	Green y-c	code		Gy		0.52	0.57	0.62		5
4	Blue x-co	ode		Bx	25 ℃	0.10	0.15	0.20	-	
	Blue y-co	ode		By		0.04	0.09	0.14		
	White x-c	code		Wx		0.26	0.31	0.36		
	White y-c	code		Wy		0.28	0.33	0.38		
	Brightnes	SS		Y		280	350	-	cd/m <sup>2</sup>	
5	Brightnes Uniform				25 ℃	80	-	-	%	6

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## 3.2 Definition of optical characteristics

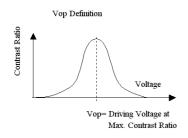
#### **Measurement condition:**

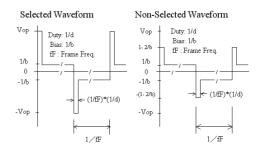
#### Transmissive and Transflective type



PHOTAL LCD-5000

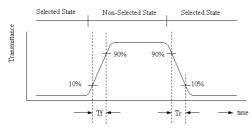
## [Note 1] Definition of LCD Driving Vop and Waveform :





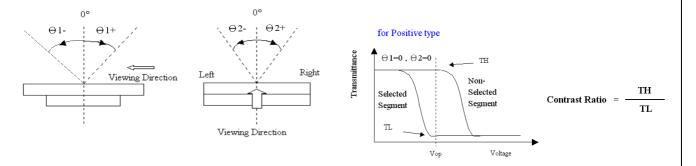
### [Note 2] Definition of Response Time

for Positive type

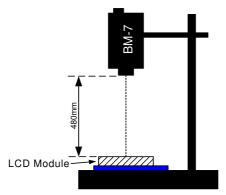


#### [Note 3] Definition of Viewing Angle:

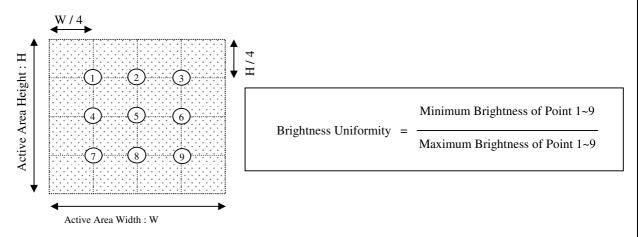
### [Note 4] Definition of Contrast Ratio:



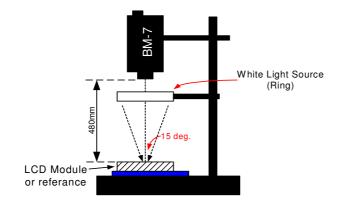
## [Note 5] Definition of measurement of Color Chromaticity and Brightness



[Note 6] Definition of Brightness Uniformity



[Note 7] Definition of Measurement of Reflectance



## 4. RELIABILITY:

Item No	Items	Condition
1	High temperature operating	70 °C , 200 hours
2	Low temperature operating	-20 °C , 200 hours
3	High temperature storage	80 °C , 200 hours
4	Low temperature storage	-30 °C , 200 hours
5	High temperature & humidity storage	60°C, 90%RH, 100 hours
6	Thermal Shock storage	-30°C, 30min.<=> 80°C, 30min. 10 Cycles
7	Vibration test	10 => 55 => 10 => 55 => 10 Hz, within 1 minute Amplitude: 1.5mm. 15 minutes for each Direction ( X,Y,Z )
8	Drop test	Packed, 100CM free fall, 6 sides, 1 corner, 3edges
9	Life time	50,000 hours 25°C, 60%RH, specification condition driving

- \* One single product test for only one item.
- \* Judgment after test: keep in room temperature for more than 2 hours.
  - Current consumption < 2 times of initial value
  - Contrast > 1/2 initial value
  - Function : work normally

#### 5. PRODUCT HANDLING AND APPLICATION

#### ☐ PRECAUTION FOR HANDLING LCM

- The LCD module contains a C-MOS LSI. People who operate the LCM should wear ESD protection eguipement to prevent ESD hurt on products.
- Do not input any signal before power is turned on.
- Do not take LCM from its packaging bag until it is assembled.
- Peel off the LCM protective film slowly since static electricity may be generated.
- Pay attention to the humidity of the work shop, 50~60%RH is satisfactory.
- Use a non-leak iron for soldering LCM.
- Do not touch the display surface or connection terminals area with bare hands. Smudges on the display surface reduce the insulation between terminals.
- Cautions for soldering to LCM:

Condition for soldering I/O terminals:

Temperature at iron tip :350°C  $\pm 15$ °C.

Soldering time: 3~4sec./ terminals.

Type of solder: Eutectic solder(rosin flux filled).

#### ☐ PRECAUTION IN USE OF LCD

- Do not contact or scratch the front surface and the contact pads of a LCD panel with hard materials such as metal or glass or with one's nail.
- To clean the surface, wipe it gently with soft cloth dampened by alcohol.
- Do not attempt to wiped off the contact pads.
- Keep LCD panels away from direct sunlight, also avoid them in high-temperature & high humidity environment for a long period.
- Do not drive LCD panels by DC voltage.
- Do not expose LCD panels to organic solvent.
- Liquid in LCD is hazardous substance. In case a contact with liquid crystal material is occured, be sure to immediately wash such material away by soap and water.
- The polarizer is easily damaged and should be handle with special care. Don't press or rub it with hard objects.

#### ☐ PRECAUTION FOR STORING AND USE OF LCM

- To avoid degradation of the device, do not store the module under the conditions of direct sunlight, high temperature or high humidity. Keep the module in bags designed to prevent static electricity charging under low temperature / normal humidity conditions(avoid high temperature / high humidity and low temperature below  $0^{\circ}$ C)
- Never use the LCD, LCM under 45 Hz, the liquid crystal will decomposition and cause permently damage on display !!

#### ☐ USING ON MEDICAL CARE, SAFETY OR HAZARDOUS APPLICATION OR SYSTEM

- For the application in medical care, safety and hazardous products or systems, an authorization from URT is required. URT will not responsible for any damage or loss which caused by the products without any authorization given by URT.
- This product is not allowed to be designed and used for military application and/or purpose.
- The delivery of this product to the countries and/or regions where the embargoes are imposed by U.N. is prohibited.
- The application and delivery of this product must comply with Startegic High-Tech Commodities (SHTC) export control and the sales to the embargoed and/or sanctioned countries or regions are strictly prohibited.

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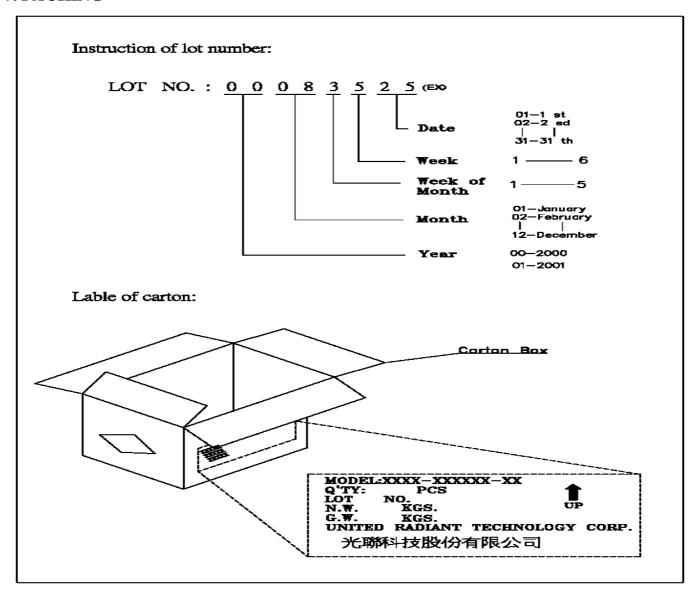


## 6. DATE CODE OF PRODUCTS

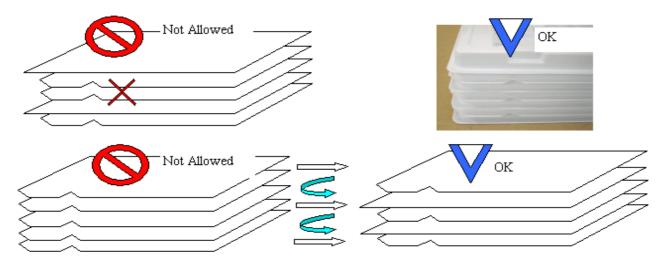
- Date code will be shown on each product :
- YY MM DD XXXX | Year Month Day - Production lots
- Example: 090508 0 0 0 3 ==> Year 2009, May., 08rd, Batch no.03

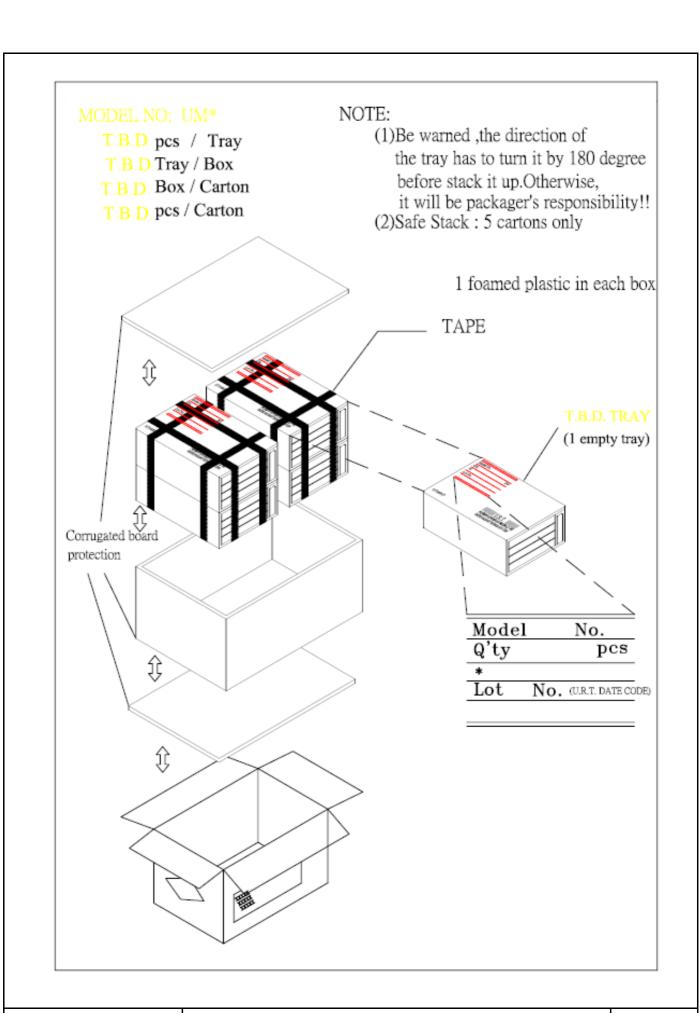
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## 7. PACKING



Packing tray must be stacked with alternated direction to each others. To tacks packing trays in same direction will cause product damaged.





#### 8. INSPECTION STANDARD

#### **8.1. QUALITY:**

THE QUALITY OF GOODS SUPPLIED TO PURCHASER SHALL COME UP TO THE FOLLOWING STANDARD.

#### 8.1.1. THE METHOD OF PRESERVING GOODS

#### 8.1.2. INCOMING INSPECTION

(A) THE METHOD OF INSPECTION

IF PURCHASER MAKE AN INCOMING INSPECTION, A SAMPLING PLAN SHALL BE APPLIED ON THE CONDITION THAT QUALITY OF ONE DELIVERY SHALL BE REGARDED AS ONE LOT.

(B) THE STANDARD OF QUALITY

ISO-2859-1 (or MIL-STD-105E), LEVEL II SINGLE PLAN.

CLASS	AQL(%)
CRITICAL	0.4 %
MAJOR	0.65 %
MINOR	1.5 %
TOTAL	1.5 %

EVERY ITEM SHALL BE INSPECTED ACCORDING TO THE CLASS.

(C) MEASURE

IF AS THE RESULT OF ABOVE RECEIVING INSPECTION, A LOT OUT IS DISCOVERED. PURCHASER SHALL BE INFORM SELLER OF IT WITHIN SEVEN DAYS. BUT FIRST SHIPMENT WITHIN FOURTEEN DAYS.

#### 8.1.3. WARRANTY POLICY

U.R.T. WILL PROVIDE ONE-YEAR WARRANTY FOR THE PRODUCTS ONLY IF UNDER SPECIFICATION OPERATING CONDITIONS. U.R.T. WILL REPLACE NEW PRODUCTS FOR THESE DEFECT PRODUCTS WHICH UNDER WARRANTY PERIOD AND BELONG TO THE RESPONSIBILITY OF U.R.T.

#### 8.2. CHECKING CONDITION

- **8.2.1.** CHECKING DIRECTION SHALL BE IN THE 45 DEGREE AREA TO FACE THE SAMPLE.
- **8.2.2.** CHECKER SHALL SEE OVER 30 cm. WITH BARE EYES FAR FROM SAMPLE AND USING 2 PCS. OF 20W FLUORESCENT LAMP.



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# 8.3. INSPECTION PLAN:

CLASS	ITEM	JUDGEMENT	CLASS
	1. OUTSIDE AND INSIDE PACKAGE	"MODEL NO." , "LOT NO." AND "QUANTITY"	Minor
PACKING &		SHOULD INDICATE ON THE PACKAGE.	
INDICATE	2. MODEL MIXED AND QUANTITY	OTHER MODEL MIXEDREJECTED	Critical
		QUANTITY SHORT OR OVERREJECTED	
	3. PRODUCT INDICATION	"MODEL NO." SHOULD INDICATE ON	Major
		THE PRODUCT	
	4. DIMENSION,	ACCORDING TO SPECIFICATION OR	
ASSEMBLY	LCD GLASS SCRATCH	DRAWING.	Major
	AND SCRIBE DEFECT.		
	5. VIEWING AREA	POLARIZER EDGE OR LCD'S SEALING LINE	Minor
		IS VISABLE IN THE VIEWING AREA	
		REJECTED	
	6. BLEMISH · BLACK SPOT ·	ACCORDING TO STANDARD OF VISUAL	Minor
	WHITE SPOT IN THE LCD	INSPECTION ( INSIDE VIEWING AREA )	
	AND LCD GLASS CRACKS	, , , , , , , , , , , , , , , , , , , ,	
	7. BLEMISH · BLACK SPOT	ACCORDING TO STANDARD OF VISUAL	Minor
APPEARANCE	WHITE SPOT AND SCRATCH	INSPECTION ( INSIDE VIEWING AREA )	
	ON THE POLARIZER		
	8. BUBBLE IN POLARIZER	ACCORDING TO STANDARD OF VISUAL	Minor
		INSPECTION ( INSIDE VIEWING AREA )	
	9. LCD'S RAINBOW COLOR	STRONG DEVIATION COLOR ( OR NEWTON	
		RING) OF LCDREJECTED.	Minor
		OR ACCORDING TO LIMITED SAMPLE	
		( IF NEEDED, AND INSIDE VIEWING AREA )	
	10. ELECTRICAL AND OPTICAL	ACCORDING TO SPECIFICATION OR	Critical
	CHARACTERISTICS	DRAWING . ( INSIDE VIEWING AREA )	
	( CONTRAST \ VOP \		
	CHROMATICITY ETC )		
ELECTRICAL	11.MISSING LINE	MISSING DOT · LINE · CHARACTER	Critical
		REJECTED	
	12.SHORT CIRCUIT	NO DISPLAY · WRONG PATTERN	Critical
	WRONG PATTERN DISPLAY	DISPLAY · CURRENT CONSUMPTION	
		OUT OF SPECIFICATION REJECTED	
	13. DOT DEFECT (FOR COLOR AND TFT)	ACCORDING TO STANDARD OF VISUAL	Minor
	( 31. 32. 31. 31. 31. 31. 31. 31. 31. 31. 31. 31	INSPECTION	

## 8.4. STANDARD OF VISUAL INSPECTION

NO.	CLASS	ITEM				JUI	DGEM	IENT				
			(A) RC	OUND TY	PE:					unit : n	nm.	
				DIAMET	ER (m	m.)	AC	CEPT	ΓABLE	Q'TY		
		· BLEMISH · BLACK SPOT ·	$\Phi \leq 0.1$					DISREGARD				
		WHITE SPOT IN THE LCD.		0.1 <	Φ	$\leq 0.2$	2		2			
				0.2 <	Φ	$\leq 0.2$	25		1			
				0.25 <	Φ				0			
8.4.1	MINOR	· BLEMISH · BLACK SPOT ·	1	NOTE: Φ=	=(LENG1	TH+WID	TH)/2					
		WHITE SPOT AND SCRATCH	(B) LIN	NER TYP	E:						unit : m	m.
		ON THE POLARIZER		LENGTH		WIDT				PTABLI		,
						W	≦0	0.03		DISRE	GARD	
				0.03 <	W	≦0	0.05		3			
				$L \leq 5.0$	i e	W	≦0	0.07		1		
			Ŀ		0.07 <	W			FOLLOV	V ROUN	D TYPE	
			Г				Ī			unit : n		
	3.4.2 MINOR I			DIAMET						LE Q'I	Ϋ́	
0.4.5		BUBBLE IN POLARIZER			Φ	≦0.		Ι	DISREC	SARD		
				0.15 <	Φ	$\leq 0$	0.5		2			
8.4.2			0.5 < Φ					0				
8.4.2			L	0.5 <	Φ				0			
8.4.2			[	0.5 <	Φ				0			
8.4.2				0.5 <	Φ				0			
8.4.2				0.5 <				AC		v 1		
8.4.2		Dat Defect			Items				C. Q'T	Y		
8.4.2		Dot Defect		Bright dot	Items				C. Q'T N≦ 4	Y		
8.4.2		Dot Defect		Bright dot Dark dot	Items				C. Q'T	Y		
8.4.2		Dot Defect		Bright dot	Items				C. Q'T N≦ 4	Y		1
8.4.2		Dot Defect		Bright dot Dark dot	Items	R	G		C. Q'T N≦ 4	Y G	В	]
8.4.2		Dot Defect		Bright dot Dark dot Define	Items	R	G		C. Q'T N≤ 4 N≤ 4		В	]
8.4.2		Dot Defect		Bright dot Dark dot Define	Items	R	G		C. Q'T N≤ 4 N≤ 4		ВВ	
8.4.2	MINOR	Dot Defect		Bright dot Dark dot Define	Items			В	C. Q'T N≤ 4 N≤ 4	G		
	MINOR	Dot Defect		Bright dot Dark dot Define	Items  B B			В	C. Q'T N≤ 4 N≤ 4	G		
	MINOR	Dot Defect		Bright dot Dark dot Define R G	Items	R	G	ВВ	C. Q'T N≤ 4 N≤ 4	G G	В	
	MINOR	Dot Defect	Pixel	Bright dot Dark dot Define R G	Items  B B  B B	R R	G G	B B	C. Q'T N≤ 4 N≤ 4 R R	G G	ВВ	ov
	MINOR	Dot Defect	Pixel  Not 1	Bright dot Dark dot Define R G R G	Items  B  B  B  B  Finition	R R of do	G G t: The	B B B	C. Q'T $N \le 4$ $N \le 4$ $R$ $R$ $R$	G G G	B B we dot	ov
	MINOR	Dot Defect	Pixel  Not 1	Bright dot Dark dot Define R G R G The de	Items  B B B G B Inition	R R of do	G G t: The	B B B e size	C. Q'T $N \le 4$ $N \le 4$ $R$ $R$ $R$ $R$ one de of a coordinate	G G Glefective	B  B  ve dot e dot.	
	MINOR	Dot Defect	Pixel  Not 1:	Bright dot Dark dot Define R G R G The de 1/2 of w	Items  B B B G B G G C C C C C C C C C C C C	R R of do ot is reports appropriate the control of	G  t: The gardee pear broken by	B B B c sized as	C. QT N≤ 4 N≤ 4 R R R	G G G defective	B  B  ve dot e dot. ged in	siz
	MINOR	Dot Defect	Pixel  Not 1:	Bright dot Dark dot Define  R G R G : The de 1/2 of w : Bright	Items  B B B G Inition dot: Do	R R of do ot is re ots app	G  t: The garded bear books display	B B size	C. Q'T N≤ 4 N≤ 4  R  R  R  c of a c one detain and uning unio	G G defective	B  B  we dot e dot. ged in ck patt	siz
	MINOR	Dot Defect	Not 1: Not 2: Not 3:	Bright dot Dark dot Define  R G R G : The de 1/2 of w : Bright in which	Items  B B B G B C C C C C C C C C C C C C C	R R n of do to is re tots appropriate in the second	G  t: The garded bear bear darder darder	B B B c size d as right blayi rk an	C. QT  N   4  R  R  R  R  cone decent and under and unched and unc	G G Gefective anchangeder black ananged	B  We dot e dot. ged in ck patt	siz err

NO.	CLASS	ITEM	JUDGEMENT	
8.4.4	MINOR	LCD GLASS CHIPPING	S X	Y > S Reject
8.4.5	MINOR	LCD GLASS CHIPPING	SXX	X or Y > S Reject
8.4.6	MAJOR	LCD GLASS GLASS CRACK	Y	Y > (1/2) T  Reject
8.4.7	MAJOR	LCD GLASS SCRIBE DEFECT	$A^{\frac{1}{7}} = A^{\frac{1}{7}} B$	<ol> <li>a&gt; L/3 , A&gt;1.5mm. Reject</li> <li>B: ACCORDING TO DIMENSION</li> </ol>
8.4.8	MINOR	LCD GLASS CHIPPING ( ON THE TERMINAL AREA )	T	$\Phi = (x+y)/2 > 2.5 \text{ mm}$ Reject
8.4.9	MINOR	LCD GLASS CHIPPING ( ON THE TERMINAL SURFACE )	T Z X	Y > (1/3) T  Reject
8.4.10	MINOR	LCD GLASS CHIPPING	T Z	Y > T Reject



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